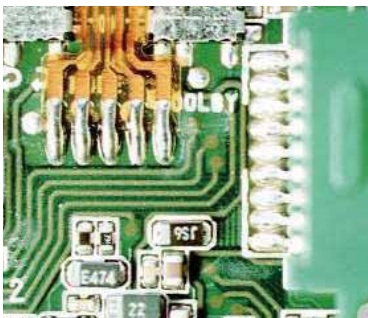


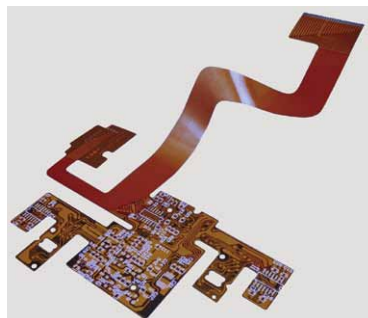
Conductive Copper Paste

for PCB proofing against EMI and Cross-over

DD paste **NF2000EX**



Rigid PCB used for copper paste wiring for jumper

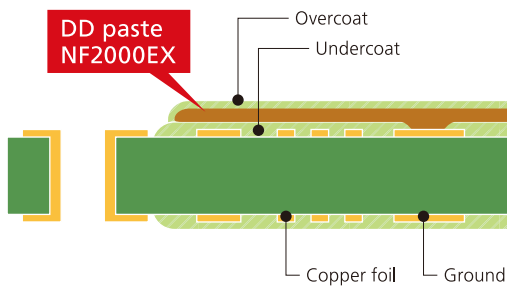


Flexible PCB proofing against EMI

Features

- ▶ Superior conductivity ($1.0 \times 10^{-4} \Omega \cdot \text{cm}$)
- ▶ Superior to silver paste in migration
- ▶ Copper powder with good cost performance

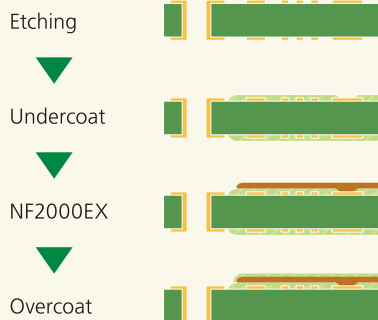
Structure



Properties & Characteristics

Filler	Copper powder
Binder	Phenolic resin
Solvent	Butyl Carbitol
Viscosity (BH type)	80±5 Pa·s
Curing condition	160°C/30min
Volume resistivity	$1.0 \times 10^{-4} \Omega \cdot \text{cm}$
Sheet resistance	25mΩ/sq.
Glass coefficient (DMA)	100°C
Pull strength	600N/cm ²

Process



Environmental test

Test items	Volume resistivity
Normal state	$1.0 \times 10^{-4} \Omega \cdot \text{cm}$
Solder dip (260°C/10sec/3cycles)	$\Delta R \leq 5\%$
Thermal aging (85°C/2000h)	$\Delta R \leq 30\%$
Heat / Humidity (60°C/95%RH/2000h)	$\Delta R \leq 30\%$
Thermal cycling (-55°C/30min↔125°C/30min/500cycles)	$\Delta R \leq 30\%$
PCT (121°C/2atm/100%RH/8h)	$\Delta R \leq 5\%$

*The data shown above is reference purpose only.